



SUGGESTED PC BOARD LAYOUT
 COMPONENT SIDE
 SCALE 2:1

LOC	DIST	REVISIONS	DATE	OWN	APP'D
AA	22				
P	UTR	DESCRIPTION			
B		REV PER ECR-08-032447	18FEB2009	DZ	SY

1 MATERIAL: HOUSING - HIGH TEMPERATURE NYLON, BLACK, IR COMPATIBLE, UL 94V-0.

TERMINALS - 0.33 [0.013] THICK PHOS BRONZE PLATED WITH 1.27 μm [0.00050] THICK HARD GOLD IN LOCALIZED AREA AND 3.81 μm [0.00150] THICK MATTE TIN IN SOLDER AREA OVER 1.27 μm [0.00050] THICK NICKEL UNDERPLATE. SHIELD - 0.254 [0.010] THICK COPPER ALLOY PLATED WITH 1.27 μm [0.00050] MINIMUM NICKEL AND 2.03 μm [0.00080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.

2 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.

3. ALL DIMENSIONS SHOWN ARE NOMINAL UNLESS OTHERWISE SPECIFIED.

4 THIS HOLE REQUIRED FOR -2 ONLY.

5 REAR GROUND TAB NOT REQUIRED FOR -1.

DESCRIPTION	PART NO.
WITH REAR PCB GROUND TAB	5406562-2
WITHOUT REAR PCB GROUND TAB	5406562-1

THIS DRAWING IS A CONTROLLED DOCUMENT.	
DIMENSIONS: mm[inches]	TOLERANCES, UNLESS OTHERWISE SPECIFIED:
0 P/LC	± -
1 P/LC	± 0.25 [0.01]
2 P/LC	± 0.13 [0.005]
3 P/LC	± -
ANGLES	± -
MATERIAL	FINISH
△	△
DWG: 16JUN2005 J. ALCORTA - DDC/KS	
CHK: WESTMAN 16JUN2005	
APP'D: FLICKINGER 16JUN2005	
PRODUCT SPEC	108-1163
APPLICATION SPEC	114-2048
WEIGHT	-
CUSTOMER DRAWING	A2 00779
SCALE	4:1
SHEET	1 of 1
REV	B